EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	11/163131	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 23:18
L2	0	("2006/0091567").URPN.	USPAT	OR	OFF	2007/04/26 23:20
L3	150634	(polymer polyimide) and (wiring wire) and (chip die element IC)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 23:24
L4	68326	3 and (package packaging housing house)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 23:24
L5	11176	4 and (encapsulant encapsulating encapsulate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 23:24
L6	18529	(polymer polyimide) same (wiring wire) same (chip die element IC)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 23:30
L7	9412	6 and (package packaging housing house)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 23:24

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L8	1504	7 and ("257"/$.ccls. and "438"/$.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 23:32
L9	2	10/711540 and (end)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/27 00:07
L10	317	7 and ("257"/787.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 23:59
L11	2	"20030103339".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/27 00:07
L12	0	"20030103339".pn. and low-K	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/27 00:08
L13	2	"20030103339".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/27 00:08
S1	918380	(packaging package)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/25 18:12

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S2	247090	S1 and (chip (integrated near circuit) "IC")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 20:13
S4	13269	S3 and (encapsulant encapsulating)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 20:13
S5	4547	S4 and (solder near ball)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 18:22
S7	35167	257/678-733.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 18:24
S8	1702	S7 and S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 18:24
S9	1427	S8 and (@ad<"20041020")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:12
S10	873	S9 and (polymer polyimide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 20:08

S11	7109	S7 and (polymer polyimide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 20:08
S12	18676	S7 and (wire wiring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 20:08
S13	5591	S12 and (polymer polyimide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 20:09
S14	5334	S13 and (chip (integrated near circuit) "IC")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 20:13
S15	1805	S14 and (encapsulant encapsulating)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 20:14
S16	1593	S15 and (@ad<"20041020")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/25 20:14
S17	1049	S15 and (@pd<"20031020")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:10

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S18	33310	(polyimide polymer) with (wiring wire)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:11
S19	919128	(packaging package)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/26 10:11
S20	6812	S18 and S19	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:11
S21	5747	S20 and (substrate carrier board wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:11
S22	4873	S21 and (@ad<"20041020")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:13
S23	35193	257/678-733.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:13
S24	18693	S23 and (wire wiring)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:13

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S25	5597	S24 and (polymer polyimide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:13
S26	5340	S25 and (chip (integrated near circuit) "IC")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:13
S27	1806	S26 and (encapsulant encapsulating)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:13
S28	1049	S27 and (@pd<"20031020")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:13
S29	4730	S22 not S28	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:20
S30	2314	S29 and ("257"/$.ccls. "438"/$.ccls.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 10:50
S31	2	10/711540	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 11:09
S33	0	("2006/0071305").URPN.	USPAT	OR	OFF	2007/04/26 14:47

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S35	439	(polymer polyimide) same (wiring wire) same (encapsulating encapsulant encapsulate) same (chip element IC (integrated near circuit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/26 18:09
S36	439	(polymer polyimide resub) same (wiring wire) same (encapsulating encapsulant encapsulate) same (chip element IC (integrated near circuit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/26 18:09
S37	1675	(polymer polyimide resin) same (wiring wire) same (encapsulating encapsulant encapsulate) same (chip element IC (integrated near circuit))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/26 18:11
S38	0	"20060091567".pn. and (polymer polymide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/26 18:12
S40	0	("2006/0091567").URPN.	USPAT	OR	OFF	2007/04/26 18:16
S41	3999	257/787.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/26 18:16
S42	1016	S41 and (polymer polyimide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/26 18:16
S43	956	S42 and (chip IC element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/26 18:17

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S45	337	S43 and wiring	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 19:17
S46	2	"20050133878".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 19:19
S47	4	("6384472"|"6545332").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 19:50
S48	48	("5436492" | "5523608" | "5703396" | "5753857" | "5898218" | "6274927" | "6353257" | "6383835" | "6384472" | "6476469").PN. OR ("6545332"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/26 19:22
S49	9	S48 and (polymer polyimide)	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/26 19:24
S51	279	257/433.ccls. and (polymer polyimide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 19:24
S52	2	10/711540 and polymer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/26 20:50

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